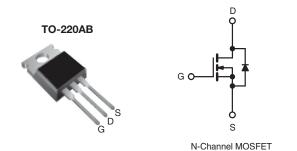


COMPLIANT

Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	10	100			
$R_{DS(on)}(\Omega)$	V _{GS} = 5.0 V 0.16				
Q _g (Max.) (nC)	2	28			
Q _{gs} (nC)	3.8				
Q _{gd} (nC)	14				
Configuration	Sir	Single			



FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Logic-Level Gate Drive
- $R_{DS(on)}$ Specified at $V_{GS} = 4 V$ and 5 V
- 175 °C Operating Temperature
- Fast Switching
- · Ease of Paralleling
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION		
Package	TO-220AB	
Lead (Pb)-free	IRL530PbF	
Lead (PD)-life	SiHL530-E3	
SnPb	IRL530	
SILD	SiHL530	

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unle	ss otherwis	se noted)			
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V_{DS}	100	V		
Gate-Source Voltage			V_{GS}	± 10	1 V	
Continuous Drain Current	V at 5.0.V	V_{GS} at 5.0 V $T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 100 ^{\circ}\text{C}$	I _D	15		
Continuous Drain Current	V _{GS} at 5.0 V			11	Α	
Pulsed Drain Current ^a		I _{DM}	60	1		
Linear Derating Factor				0.59	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	290	mJ	
Repetitive Avalanche Current ^a			I _{AR}	15	Α	
Repetitive Avalanche Energy ^a			E _{AR}	8.8	mJ	
Maximum Power Dissipation $T_C = 25 ^{\circ}C$		P_{D}	88	W		
Peak Diode Recovery dV/dt ^c			dV/dt	5.5	V/ns	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	- °C		
Soldering Recommendations (Peak Temperature) for 10 s			-			300 ^d
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N · m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. V_{DD} = 25 V, starting T_J = 25 °C, L = 1.9 mH, R_g = 25 Ω I_{AS} = 15 A (see fig. 12).
- c. $I_{SD} \le 15$ A, $dI/dt \le 140$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 1\bar{7}5$ °C.
- d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62		
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	1.7		

PARAMETER	SYMBOL	TEST (TEST CONDITIONS		TYP.	MAX.	UNIT
Static						•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0$	V, I _D = 250 μA	100	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference t	o 25 °C, I _D = 1 mA	-	0.14	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_0$	_{GS} , I _D = 250 μA	1.0	-	2.0	V
Gate-Source Leakage	I _{GSS}	Vo	$GS = \pm 10$	-	-	± 100	nA
Zava Cata Valtaga Dyain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V		-	-	25	
Zero Gate Voltage Drain Current		$V_{DS} = 80 \text{ V}, V_{0}$	_{GS} = 0 V, T _J = 150 °C	-	-	250	μA
Data Carana Car Olata Basistana		V _{GS} = 5.0 V	I _D = 9.0 A ^b	-	-	0.16	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 4.0 V	I _D = 7.5 A ^b	-	-	0.22	Ω
Forward Transconductance	9 _{fs}	$V_{DS} = 50$	0 V, I _D = 9.0 A ^b	6.4	-	-	S
Dynamic		1		,			
Input Capacitance	C _{iss}	V	0 V	-	930	-	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$		-	250	-	pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0 ľ	MHz, see fig. 5	-	57	-	
Total Gate Charge	Qg			-	-	28	
Gate-Source Charge	Q _{gs}	$V_{GS} = 5.0 \text{ V}$	$I_D = 15 \text{ A}, V_{DS} = 80 \text{ V},$ see fig. 6 and 13^b	-	-	3.8	nC
Gate-Drain Charge	Q _{gd}		See fig. 6 and 16	-	-	14	
Turn-On Delay Time	t _{d(on)}		1	-	4.7	-	
Rise Time	t _r	V 5	50 V I ₋ - 15 Δ	-	100	-	
Turn-Off Delay Time	t _{d(off)}	$R_g = 12 \Omega, R_D$	$_{0} = 32 \Omega$, see fig. 10 ^b	-	22	-	ns
Fall Time	t _f	$V_{DD} = 50 \text{ V}, I_D = 15 \text{ A},$		-			
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from		-	4.5	-	-11
Internal Source Inductance	L _S	package and ce die contact	nter of	-	7.5	-	nH
Drain-Source Body Diode Characteristic	s					•	
Continuous Source-Drain Diode Current	IS	MOSFET symbol showing the		-	-	15	Α
Pulsed Diode Forward Current ^a	I _{SM}	integral reverse p - n junction did	ode	-	-	60	A
Body Diode Voltage	V_{SD}	T _J = 25 °C, I ₅	$_{S} = 15 \text{ A}, V_{GS} = 0 \text{ V}^{b}$	-	-	2.5	V
Body Diode Reverse Recovery Time	t _{rr}	T 25 °C !	15 A, dl/dt = 100 A/µsb	-	150	200	ns
Body Diode Reverse Recovery Charge	Q_{rr}	1J = 23 O, IF =	10 A, αι/αι = 100 A/μS ⁵	-	0.93	1.4	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-	on time is negligible (turr	n-on is do	minated b	y L _S and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

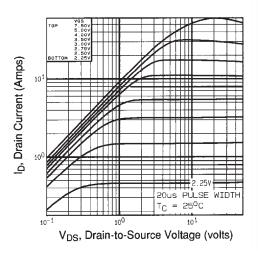


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

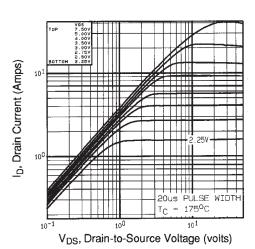


Fig. 2 - Typical Output Characteristics, $T_C = 175$ °C

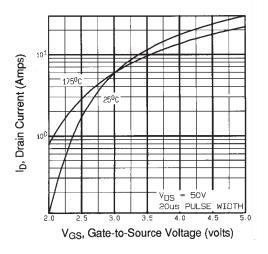


Fig. 3 - Typical Transfer Characteristics

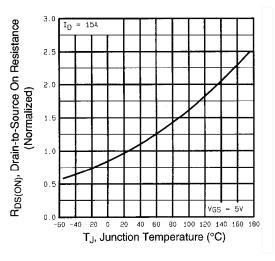


Fig. 4 - Normalized On-Resistance vs. Temperature



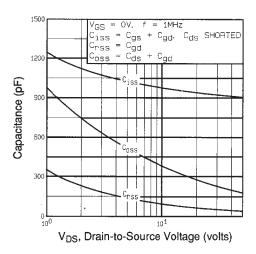


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

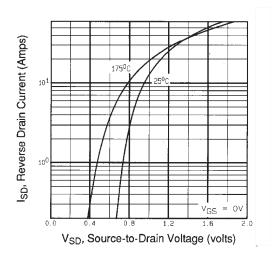


Fig. 7 - Typical Source-Drain Diode Forward Voltage

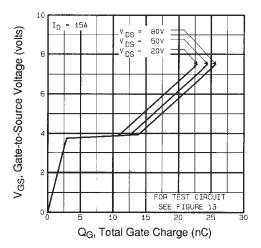


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

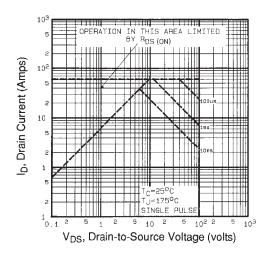


Fig. 8 - Maximum Safe Operating Area





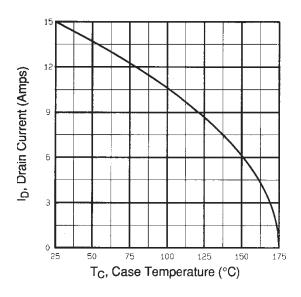


Fig. 9 - Maximum Drain Current vs. Case Temperature

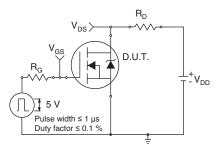


Fig. 10a - Switching Time Test Circuit

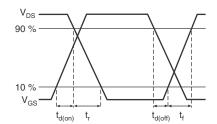


Fig. 10b - Switching Time Waveforms

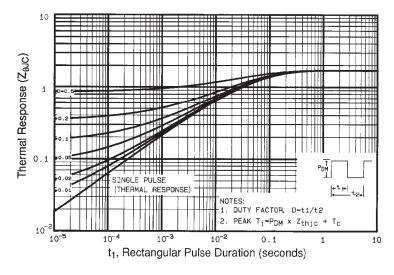


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



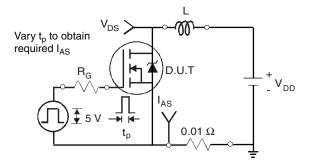


Fig. 12a - Unclamped Inductive Test Circuit

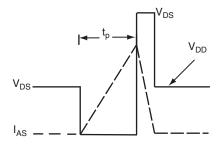


Fig. 12b - Unclamped Inductive Waveforms

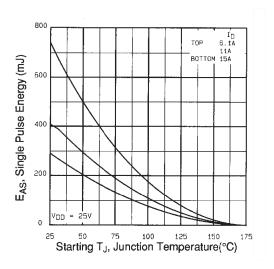


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

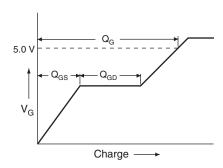


Fig. 13a - Basic Gate Charge Waveform

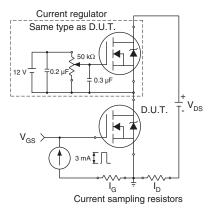
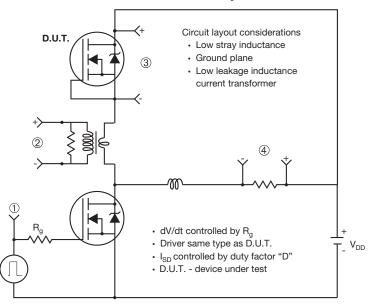


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



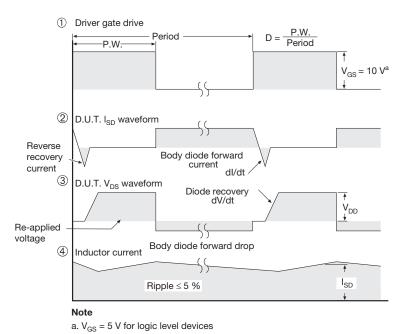


Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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